and a fine metal <u>or metal alloy conductive</u> powder having an average [primary] particle size within a range of from 2 to 30 nm and said solvent contains [at least one of] from 1 to 30 wt.% propylene glycol methylether[, from 1 to 30 wt.%] <u>or</u> isopropylgycol <u>or</u> [and] from 1 to 10 wt.% 4-hydroxy-4-methyl-2-pentanone, and the dispersant is a surfactant or polymeric

dispersant.--

a solvent containing a dispersant [said solvent comprising a dispersed solution formed by dispersing] and from 0.5 to 15 wt.% of a fine metal or metal alloy conductive powder having an average primary particle size within a range of 5 to 50 nm; and [said fine metal powder forms] secondary particles having a particle size distribution represented by a 10% cumulative particle size up to 60 nm, a 50% cumulative particle size in a range of from 50 to 150 nm and a 90% cumulative particle size in the range of from 80 to 500 nm.--

Claim 9, line 2, delete "and" and insert therefor --an--.

Claim 16, lines 2-3, delete "in the absence" and insert therefor --free---.

(Amended) A conductive film forming composition comprising [a dispersed solution formed by dispersing] a fine metal or metal alloy conductive powder having a [primary] particle size of up to 20 nm in an amount within the range of from 0.20 to 0.50 wt.% in an organic solvent containing water, wherein said solvent contains (1) a surfactant in an amount in the range of from 0.0020 to 0.080 wt.% containing a perfluoro group and/or (2) a compound selected from the group consisting of a polyhydric alcohol, polyalkylene glycol and a monoalkylether derivative thereof in a total amount in the range of from 0.10 to 3.0 wt.%.--

(Amended) A <u>dilutable</u> conductive film forming composition comprising a

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